



Advanced Metallization Conference 2006 (AMC 2006): Volume 22 (Hardback)

By -

Materials Research Society, United States, 2007. Hardback. Condition: New. Language: English . Brand New Book. The Advanced Metallization Conference 2006 - held in Tokyo and San Diego, California - highlights both current state-of-the-art and ongoing challenges associated with multilevel interconnects. Technical leaders from around the world gathered to discuss developments in the integration of low-dielectric constant materials with copper-based metallization, and advances in the means by which process- or stress-induced damage can be mitigated and reliability of the interconnect system improved. Contributions to the volume focus on design, development and modeling of advanced on-chip and multichip interconnect architectures and real-world implementation of optimized designs, materials and processes for production of leading-edge microelectronic devices. A keynote address by H.-S. Philip Wong, Stanford University, on Nanostructured Materials for Interconnects is featured.



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Reviews

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